Product Change Notification - KSRA-23ENWX184

Date:

22 Aug 2019

Product Category:

Others; Computing Embedded Controllers

Affected CPNs:

Notification subject:

CCB 3780 Final Notice: Qualification of MMT as an additional assembly site for selected products of the 65nm GF wafer technology available in 128L TQFP (14x14x1mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected products of the 65nm GF wafer technology available in 128L TQFP (14x14x1mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at ASE assembly site using palladium coated copper (PdCu) bond wire, 1076WA die attach, and G631H molding compound material.

Post Change:

Assembled at ASE assembly site using palladium coated copper (PdCu) bond wire, 1076WA die attach, and G631H molding compound material. Assembled at MMT assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, 3280 die attach, and G700HA molding compound material.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	ASE Inc. / ASE	ASE Inc. / ASE	Microchip Technology Thailand (Branch) / MMT
Wire material	PdCu	PdCu	CuPdAu
Die attach material	1076WA	1076WA	3280
Molding compound material	G631H	G631H	G700HA
Lead frame material	C7025	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

September 22, 2019 (date code: 1939)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2019					-->	August 2019					September 2019				
Workweek	14	15	16	17	18		31	32	33	34	35	36	37	38	39	40
Initial PCN Issue Date				X												
Qual Report Availability										X						
Final PCN Issue Date										X						
Estimated Implementation Date															X	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

April 26, 2019: Issued initial notification.

August 22, 2019: Issued final notification. Attached the Qualification Report Provided estimated first ship date to be on September 22, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-23ENWX184_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

MEC1322-NU
MEC1324-NU
MEC1322-NU-C0
MEC1322I-NU-C0
MEC1404-NU
MEC1418-NU
MEC1406-NU
MEC1408-NU
MEC1404-NU-D0
MEC1406-NU-D0
MEC1416-NU-D0
MEC1414-NU
MEC1416-NU
MEC1418-NU-D0
MEC1418-I/NU
MEC1414-I/NU
MEC1416-I/NU
MEC1428-NU-C1
MEC1428-I/NU-C1